









RESHAPING THE ELECTRONICS INDUSTRY WITH ADDITIVELY MANUFACTURED ELECTRONICS

Design flexibility beyond the traditional boundaries

Breakthrough solution for traditional development challenges

One-stop shop for design and manufacturing







PRINTER CAPABILITIES

Build Volume	160 mm x 160 mm x 3 mm
Inks	Optimized silver nano particles and dielectric inks
Supported File Formats	All major ECAD and MCAD Software, ODB++, Gerber & Excellon, STLs
Resolution	18 μm (x), 18 μm (y), 10 μm (z)
Min. Line/Space	75 µm traces/100 µm spacing
Min. BGA Pitch	350 µm
Min. Via	150 µm
Min. Dielectric Layer Thickness	10.0μm
Min. Conductive Layer Thickness	1.18µm
Conductivity (Relative to Copper)	30% +/-5%
Dielectric Constant (Dk) @ 2GHz/15GHz	2.77/2.78
Tangential Loss (Df) @ 2GHz/15GHz	0.015/0.018

PRINTER SPECIFICATIONS

Dimensions	1,400 mm x 800 mm x 1,800 mm
Weight	520 kg, (1,150 lbs)
Power Supply*	230VAC, 20A, 50-60Hz
Network Connectivity	Ethernet TCP/IP 10/100/1000
Operational Humidity	Above 35 % non-condensing
Operational Temperature	18°C (64°F) to 28°C (82°F)
Regulatory Compliance	UL, CE, FCC
Deposition Technology	Piezo drop-on-demand inkjet
Number of Printheads	2, one for each ink: conductive and dielectric
Software	FLIGHT Software Suite (Design, Verification, Pre-Production)

^{*} Must use UPS (Uninterruptible Power Supply)

